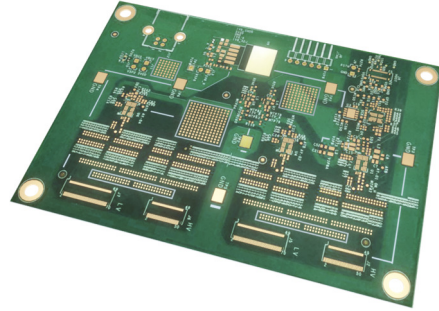


We are constantly innovating



Feature	Standar	Advanced
Number of Layers	24 Layers	36 Layers
Stack-up Type	Any Layer	Any Layer
Minimum Dielectric Thickness	0.075mm	0.05mm
Minimum Copper thickness (Base)	1/3 oz	1/4 oz
Minimum Trace Width / Spacing	75um / 75um	40um / 50um
Aspect Ratio (Blind Hole)	0.95:1	1.3:1
Minimum Pitch	350um	200um
Filled Via Dimple – Maximum	20um	10um
Laser Blind Via / Target Land	75um / 180um	65um / 165um
Back-drill	Minimum Size: 0.4mm Minimum STUB: 6mil Back-drill to Copper: 5mil minimum	Minimum Size: 0.35mm Minimum STUB: 5mil Back-drill to Copper: 5mil minimum
Layer Registration	≤12 Layers: 4mil minimum >12 Layers: 5mil minimum	≤12 Layers: 3mil minimum >12 Layers: 4mil minimum